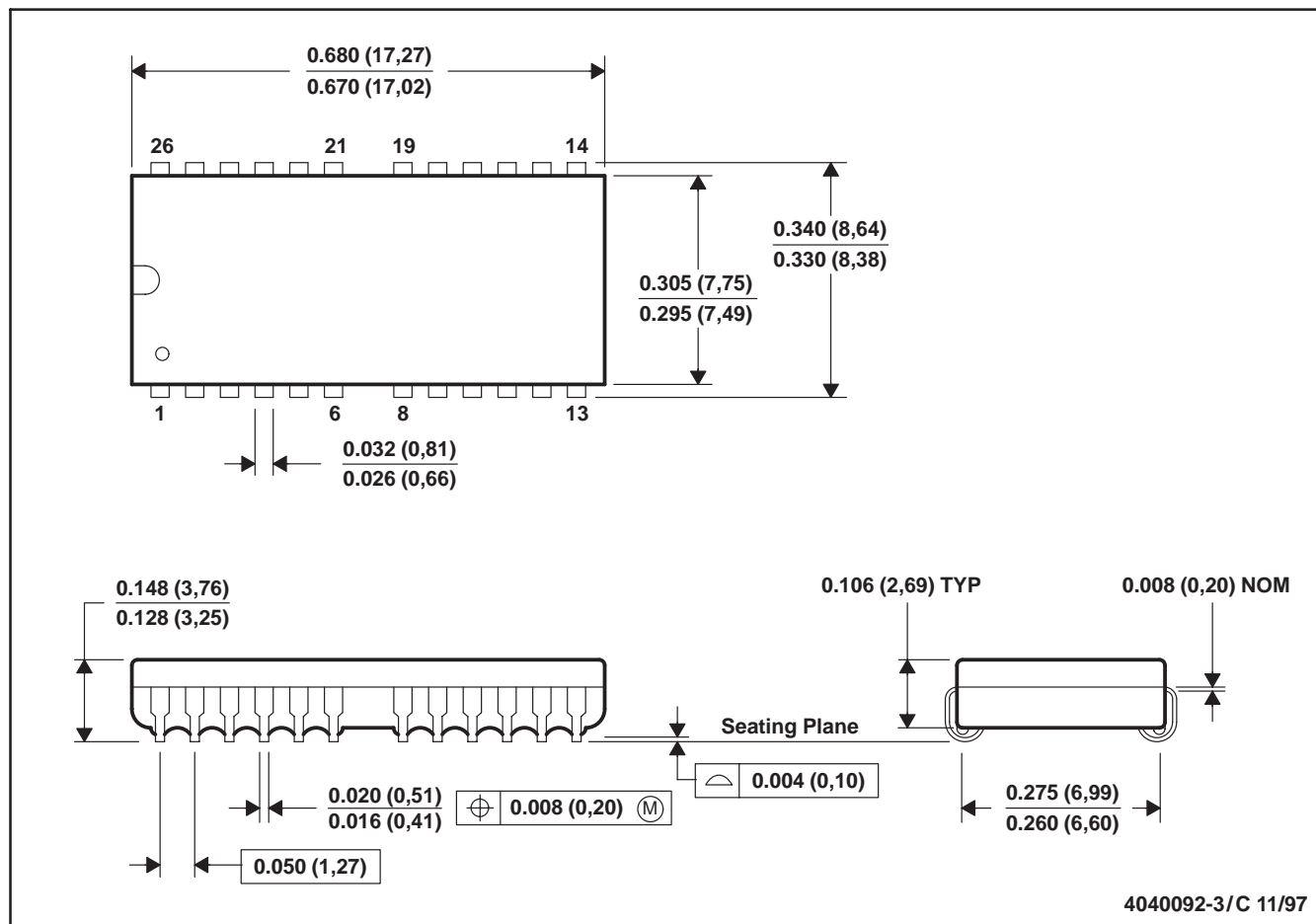


## DJ (R-PDSO-J24/26)

## PLASTIC SMALL-OUTLINE J-LEAD PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Plastic body dimensions do not include mold protrusion. Maximum mold protrusion is 0.006 (0,15) per side.

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